

Title: METAL PLATING METHOD, PRETREATMENT AGENT, AND SEMICONDUCTOR WAFER
AND SEMICONDUCTOR DEVICE OBTAINED USING THESE
Inventors: Toru IMORI et al
Serial No.: Unknown
Docket No.: Komatsu Case 267A

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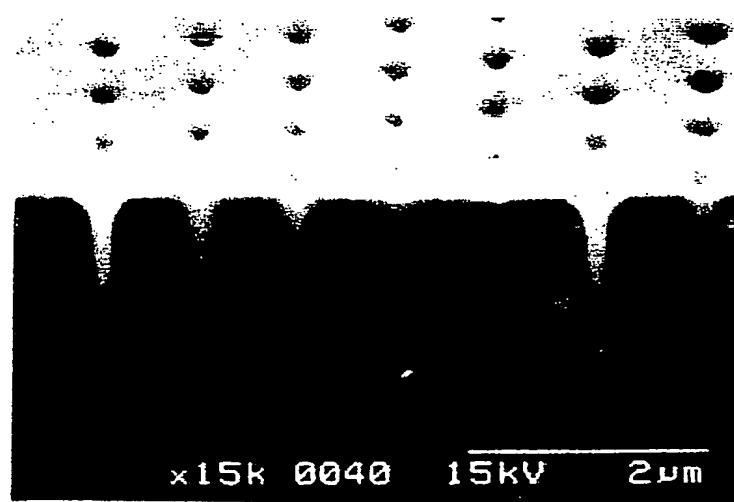


FIG. 1

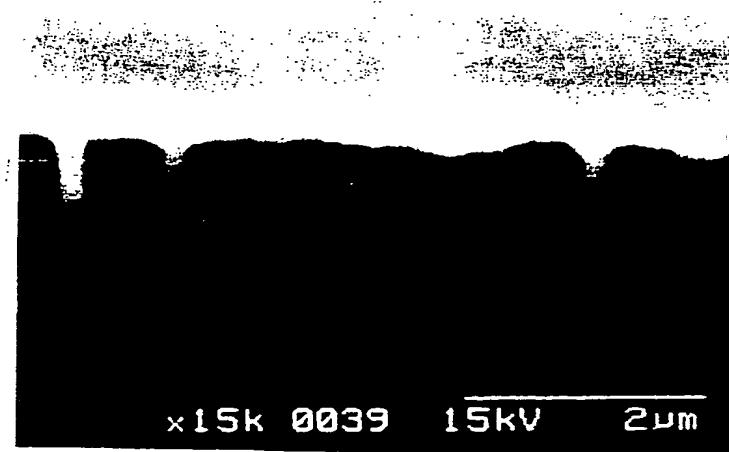


FIG. 2

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